

# SN54ALS00A, SN54AS00, SN74ALS00A, SN74AS00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

SDAS187A – APRIL 1982 – REVISED DECEMBER 1994

- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

## description

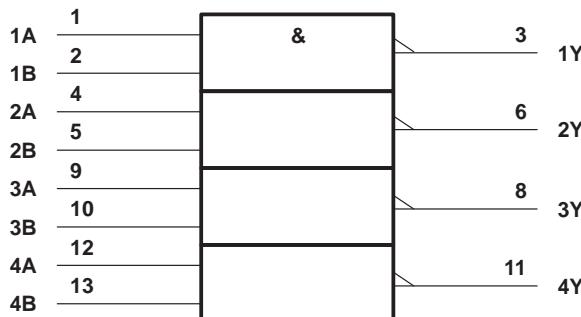
These devices contain four independent 2-input positive-NAND gates. They perform the Boolean functions  $Y = A \bullet \bar{B}$  or  $Y = \bar{A} + \bar{B}$  in positive logic.

The SN54ALS00A and SN54AS00 are characterized for operation over the full military temperature range of  $-55^{\circ}\text{C}$  to  $125^{\circ}\text{C}$ . The SN74ALS00A and SN74AS00 are characterized for operation from  $0^{\circ}\text{C}$  to  $70^{\circ}\text{C}$ .

FUNCTION TABLE  
(each gate)

INPUTS		OUTPUT
A	B	Y
H	H	L
L	X	H
X	L	H

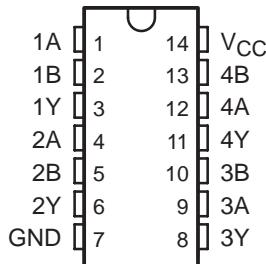
## logic symbol†



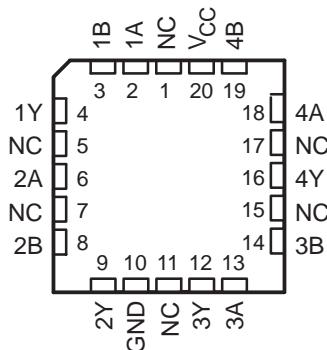
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

SN54ALS00A, SN54AS00 . . . J PACKAGE  
SN74ALS00A, SN74AS00 . . . D OR N PACKAGE  
(TOP VIEW)



SN54ALS00A, SN54AS00 . . . FK PACKAGE  
(TOP VIEW)

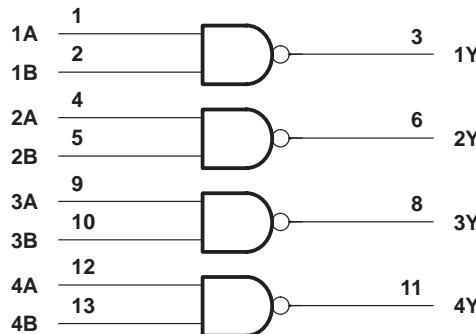


NC – No internal connection

# **SN54ALS00A, SN54AS00, SN74ALS00A, SN74AS00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES**

SDAS187A – APRIL 1982 – REVISED DECEMBER 1994

## logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions

		SN54ALS00A			SN74ALS00A			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage	2			2			V
V <sub>IL</sub>	Low-level input voltage		0.8 <sup>†</sup>			0.8		V
			0.7 <sup>§</sup>					
I <sub>OH</sub>	High-level output current			-0.4			-0.4	mA
I <sub>OL</sub>	Low-level output current			4			8	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

† Applies over temperature range -55°C to 70°C

§ Applies over temperature range 70°C to 125°C

# SN54ALS00A, SN54AS00, SN74ALS00A, SN74AS00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES

SDAS187A – APRIL 1982 – REVISED DECEMBER 1994

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54ALS00A			SN74ALS00A			UNIT
		MIN	TYPT <sup>†</sup>	MAX	MIN	TYPT <sup>†</sup>	MAX	
$V_{IK}$	$V_{CC} = 4.5 \text{ V}$ , $I_I = -18 \text{ mA}$			-1.2			-1.5	V
$V_{OH}$	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ , $I_{OH} = -0.4 \text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
$V_{OL}$	$V_{CC} = 4.5 \text{ V}$	$I_{OL} = 4 \text{ mA}$		0.25	0.4	0.25	0.4	V
		$I_{OL} = 8 \text{ mA}$				0.35	0.5	
$I_I$	$V_{CC} = 5.5 \text{ V}$ , $V_I = 7 \text{ V}$			0.1			0.1	mA
$I_{IH}$	$V_{CC} = 5.5 \text{ V}$ , $V_I = 2.7 \text{ V}$			20			20	$\mu\text{A}$
$I_{IL}$	$V_{CC} = 5.5 \text{ V}$ , $V_I = 0.4 \text{ V}$			-0.1			-0.1	mA
$I_O^{\ddagger}$	$V_{CC} = 5.5 \text{ V}$ , $V_O = 2.25 \text{ V}$	-20	-112	-30	-112			mA
$I_{CCH}$	$V_{CC} = 5.5 \text{ V}$ , $V_I = 0$		0.5	0.85	0.5	0.85		mA
$I_{CCL}$	$V_{CC} = 5.5 \text{ V}$ , $V_I = 4.5 \text{ V}$	1.5	3	1.5	3			mA

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^\circ\text{C}$ .

<sup>‡</sup> The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$ , $C_L = 50 \text{ pF}$ , $R_L = 500 \Omega$ , $T_A = \text{MIN to MAX}^{\$}$				UNIT	
			SN54ALS00A		SN74ALS00A			
			MIN	MAX	MIN	MAX		
$t_{PLH}$	A or B	Y	3	15	3	11	ns	
			2	9	2	8		

<sup>§</sup> For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

# **SN54ALS00A, SN54AS00, SN74ALS00A, SN74AS00 QUADRUPLE 2-INPUT POSITIVE-NAND GATES**

SDAS187A – APRIL 1982 – REVISED DECEMBER 1994

**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>**

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### **recommended operating conditions**

		SN54AS00			SN74AS00			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V <sub>IH</sub>	High-level input voltage		2		2			V
V <sub>IL</sub>	Low-level input voltage			0.8			0.8	V
I <sub>OH</sub>	High-level output current			-2			-2	mA
I <sub>OL</sub>	Low-level output current			20			20	mA
T <sub>A</sub>	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	SN54AS00			SN74AS00			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$			-1.2			-1.2	V
$V_{OH}$	$V_{CC} = 4.5\text{ V to }5.5\text{ V}$ , $I_{OH} = -2\text{ mA}$	$V_{CC} - 2$			$V_{CC} - 2$			V
$V_{OL}$	$V_{CC} = 4.5\text{ V}$ , $I_{OL} = 20\text{ mA}$		0.35	0.5		0.35	0.5	V
$I_I$	$V_{CC} = 5.5\text{ V}$ , $V_I = 7\text{ V}$			0.1			0.1	mA
$I_{IH}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 2.7\text{ V}$			20			20	$\mu\text{A}$
$I_{IL}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 0.4\text{ V}$			-0.5			-0.5	mA
$I_O^{\$}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 2.25\text{ V}$	-30	-112		-30	-112		mA
$I_{CCH}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 0$		2	3.2		2	3.2	mA
$I_{CCI}$	$V_{CC} = 5.5\text{ V}$ , $V_I = 4.5\text{ V}$		10.8	17.4		10.8	17.4	mA

<sup>‡</sup>All typical values are at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$ .

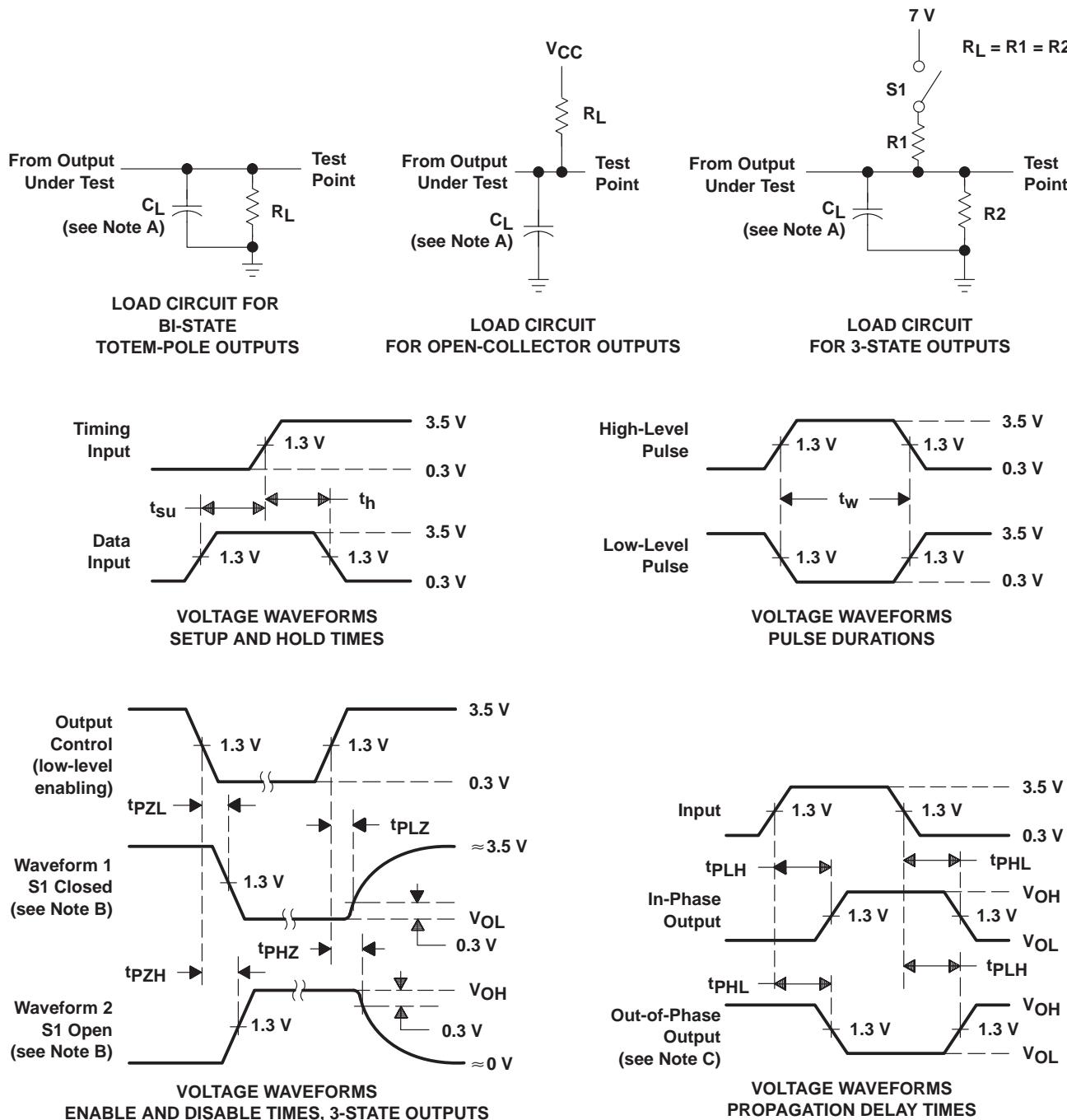
§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current,  $I_{OS}$ .

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4.5 V to 5.5 V, C <sub>L</sub> = 50 pF, R <sub>L</sub> = 500 Ω, T <sub>A</sub> = MIN to MAX <sup>1</sup>				UNIT	
			SN54AS00					
			MIN	MAX	MIN	MAX		
			1	5	1	4.5		
t <sub>PLH</sub>	A or B	Y	1	5	1	4	ns	
t <sub>PHI</sub>			1	5	1	4		

¶ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

PARAMETER MEASUREMENT INFORMATION  
SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



NOTES: A.  $C_L$  includes probe and jig capacitance.  
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.  
 C. When measuring propagation delay items of 3-state outputs, switch S1 is open.  
 D. All input pulses have the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $t_r = t_f = 2 \text{ ns}$ , duty cycle = 50%.  
 E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-86833012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8683301DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
JM38510/37001B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/37001BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54ALS00AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN54ALS00J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SN74ALS00AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS00AN3	OBsolete	PDIP	N	14		TBD	Call TI	Call TI
SN74ALS00ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS00ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS00ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00N	ACTIVE	PDIP	N	14	25	Pb-Free	CU NIPDAU	N / A for Pkg Type

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
(RoHS)								
SN74AS00NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74AS00NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00NSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74AS00NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS00AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS00AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type
SNJ54ALS00AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SNJ54AS00FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54AS00J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

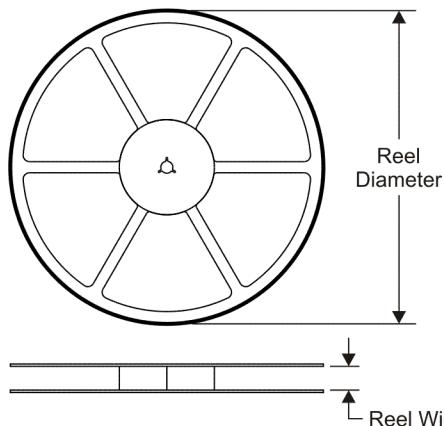
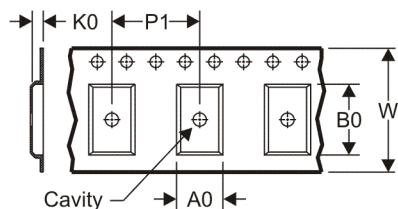
**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

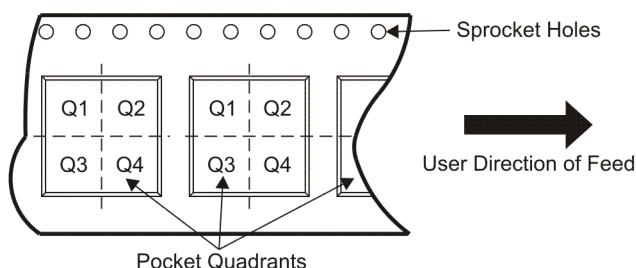
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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**TAPE AND REEL INFORMATION**
**REEL DIMENSIONS**

**TAPE DIMENSIONS**


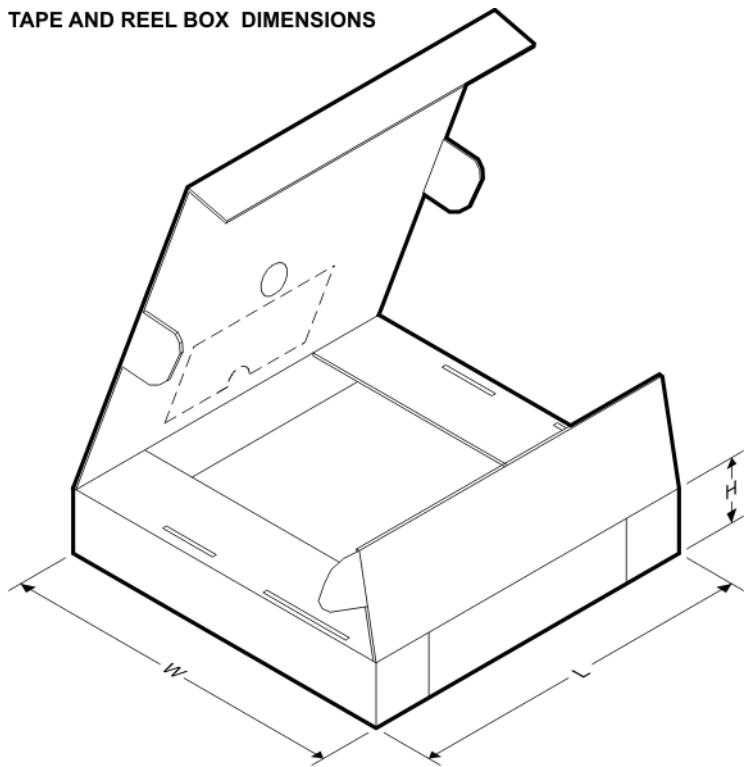
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS00ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
SN74ALS00ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74ALS00ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN74AS00DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
SN74AS00NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

**TAPE AND REEL BOX DIMENSIONS**



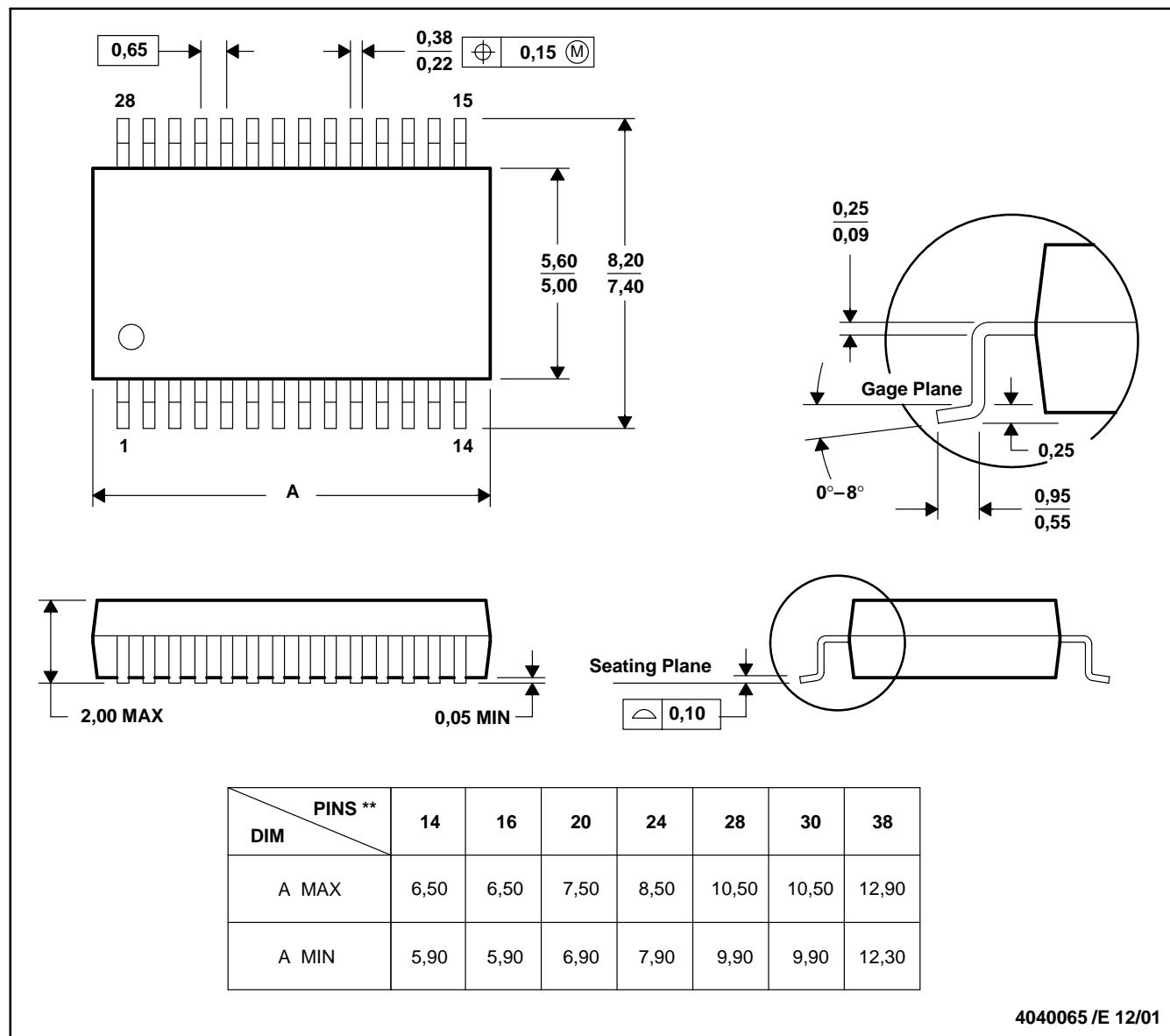
\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS00ADBR	SSOP	DB	14	2000	346.0	346.0	33.0
SN74ALS00ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74ALS00ANSR	SO	NS	14	2000	346.0	346.0	33.0
SN74AS00DR	SOIC	D	14	2500	346.0	346.0	33.0
SN74AS00NSR	SO	NS	14	2000	346.0	346.0	33.0

## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

28 PINS SHOWN

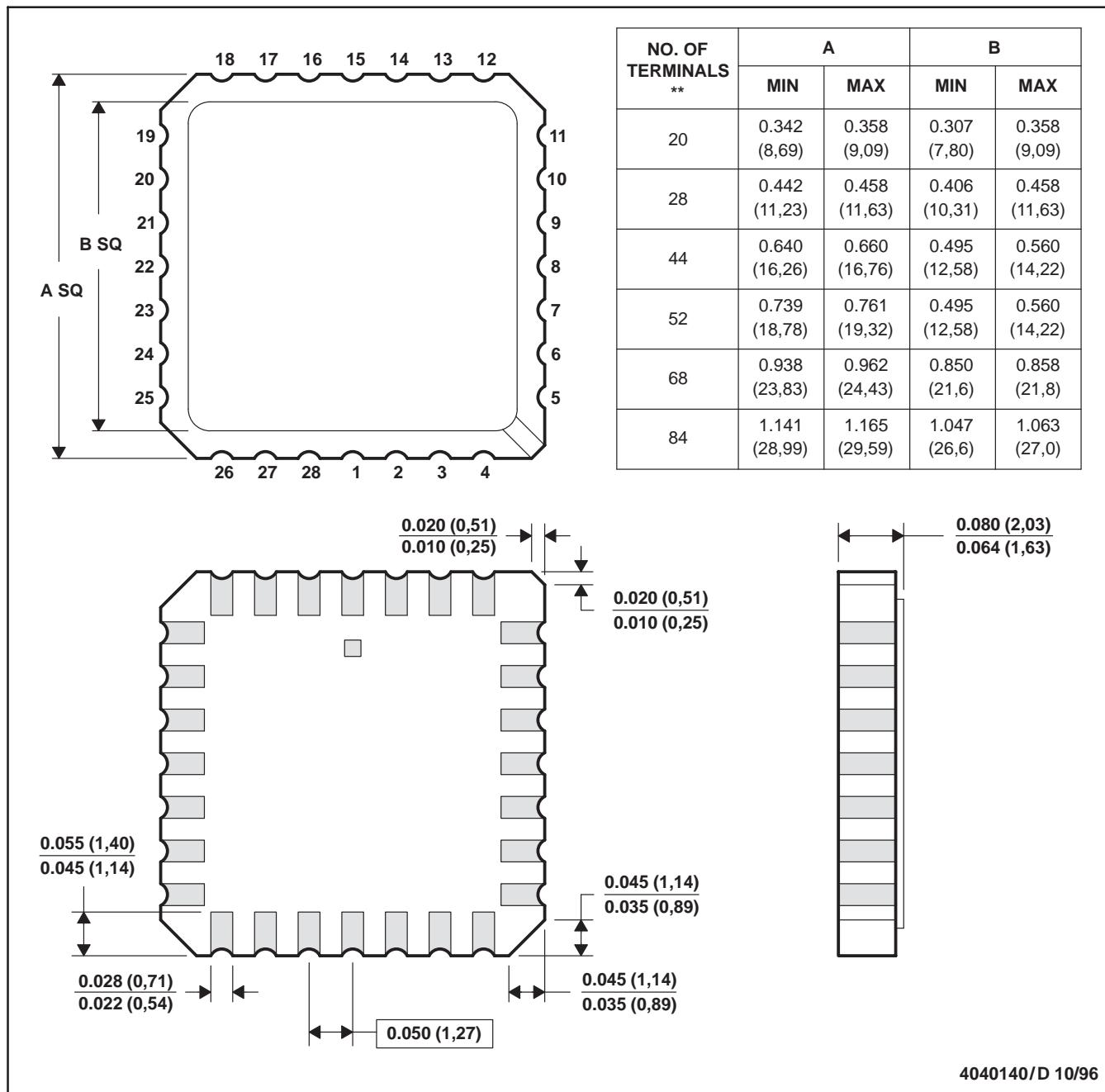


NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-150

## FK (S-CQCC-N\*\*)

## LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. The terminals are gold plated.

E. Falls within JEDEC MS-004

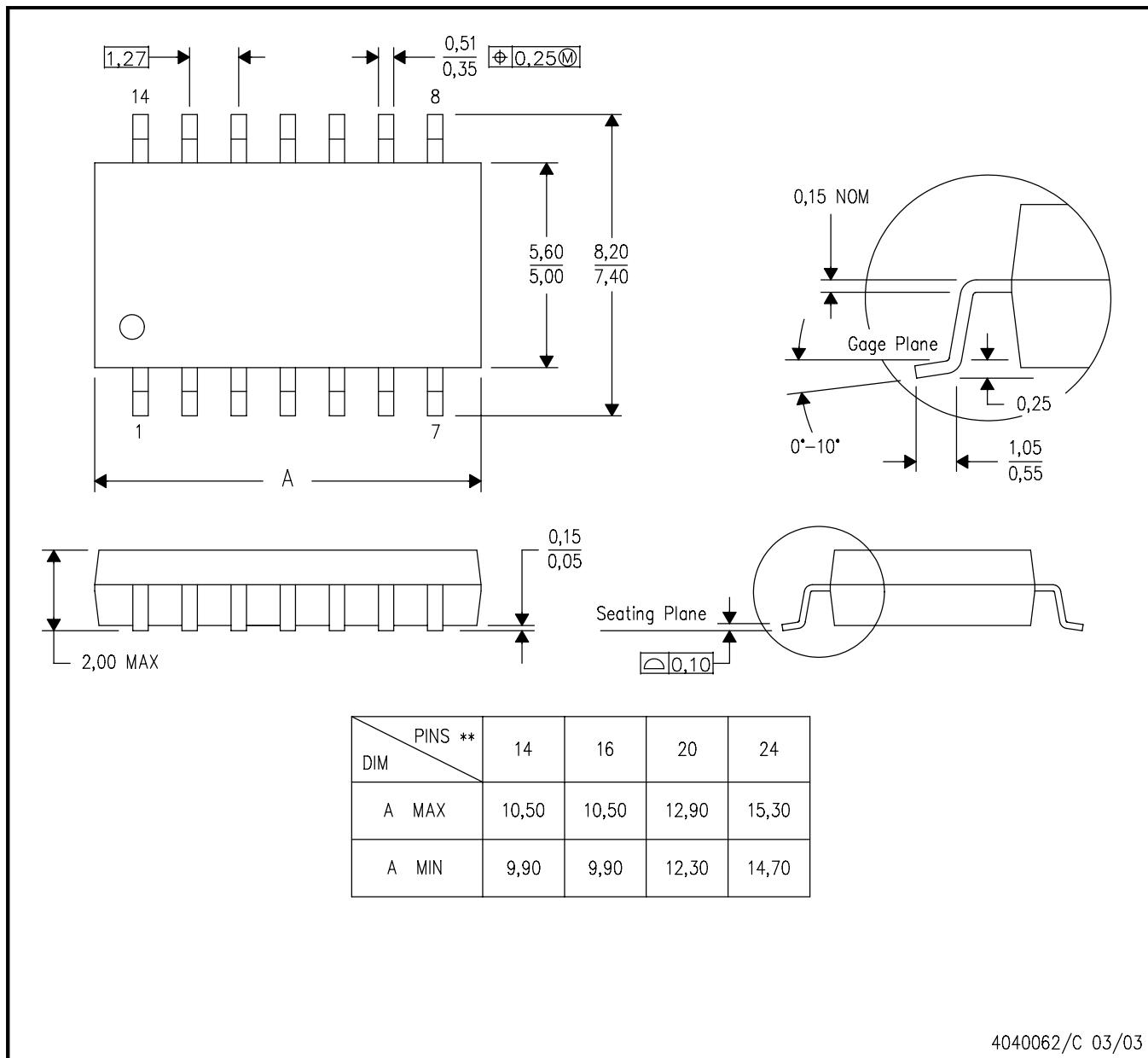
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## MECHANICAL DATA

**NS (R-PDSO-G\*\*)**

## PLASTIC SMALL-OUTLINE PACKAGE

**14-PINS SHOWN**



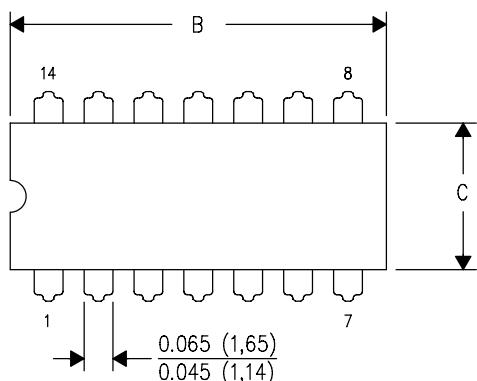
NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

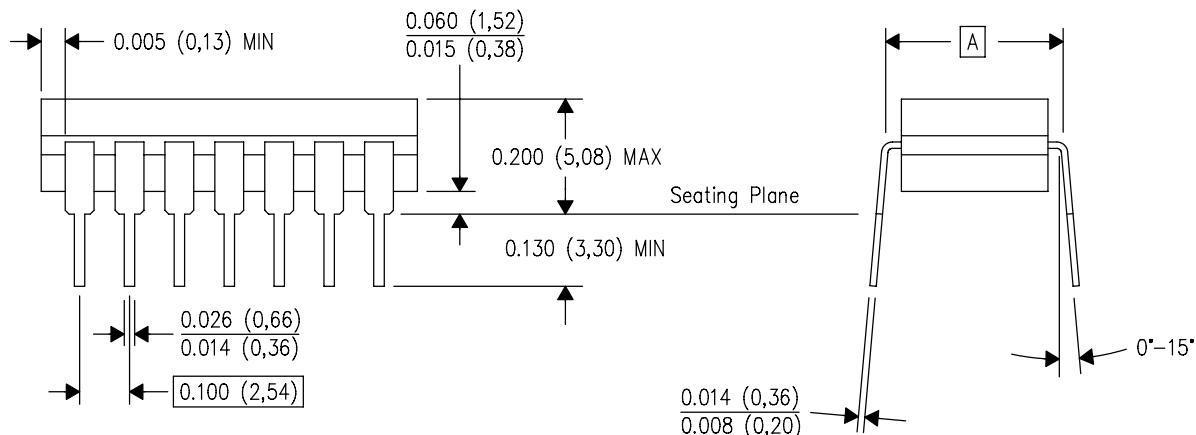
J (R-GDIP-T\*\*)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

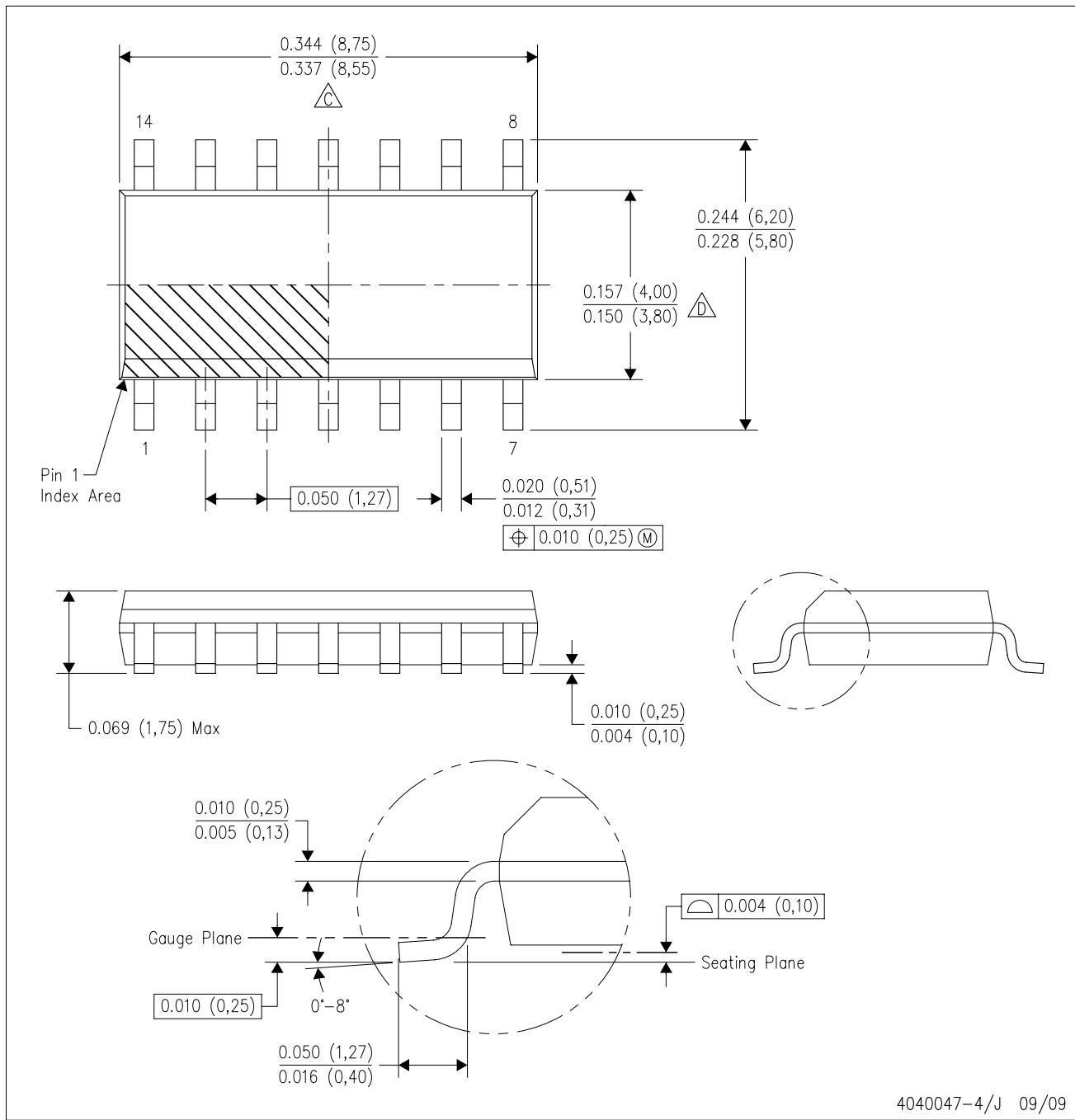


4040083/F 03/03

NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.  
C. This package is hermetically sealed with a ceramic lid using glass frit.  
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.  
E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

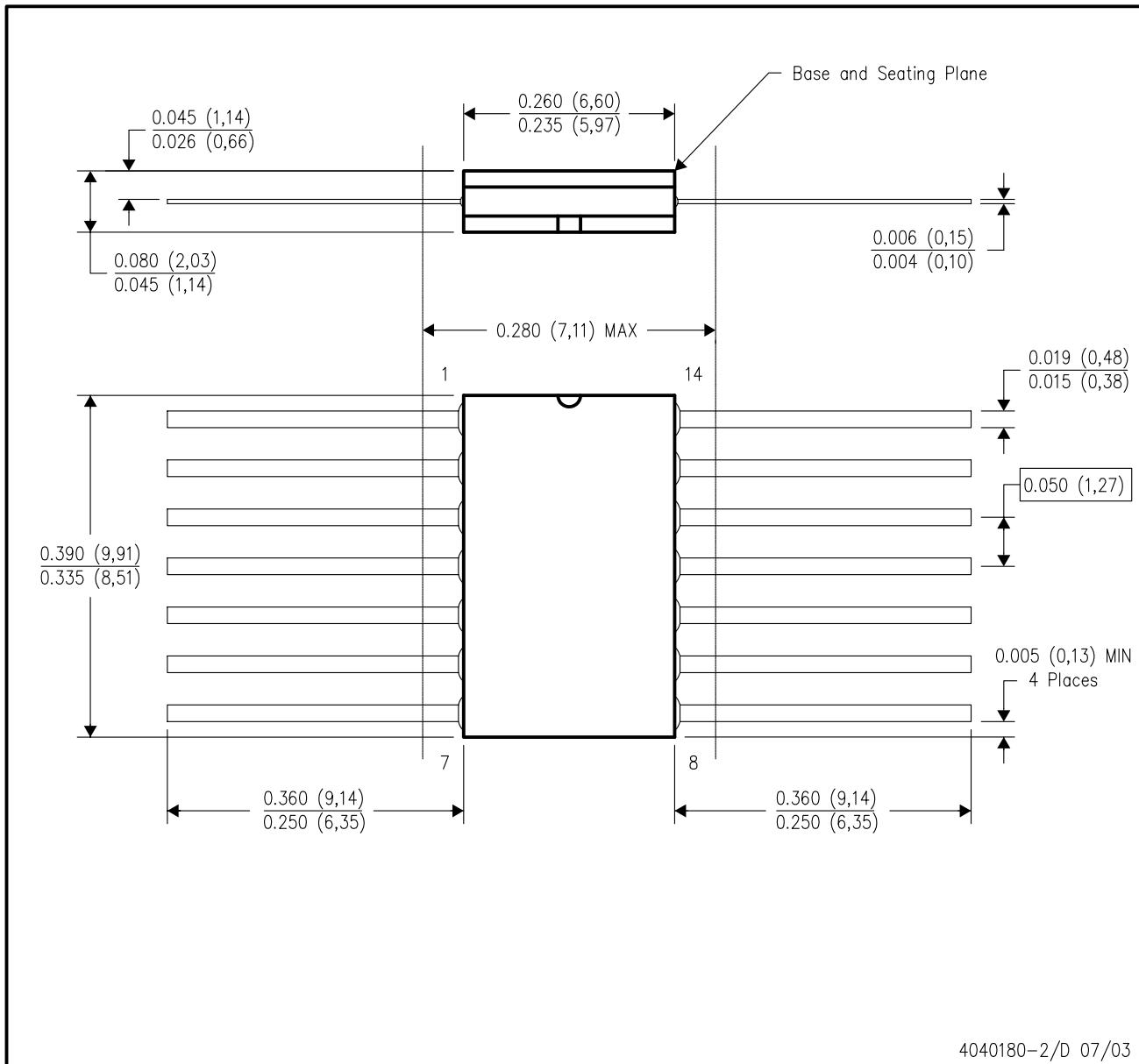
**Symbol C:** Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

**Symbol D:** Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



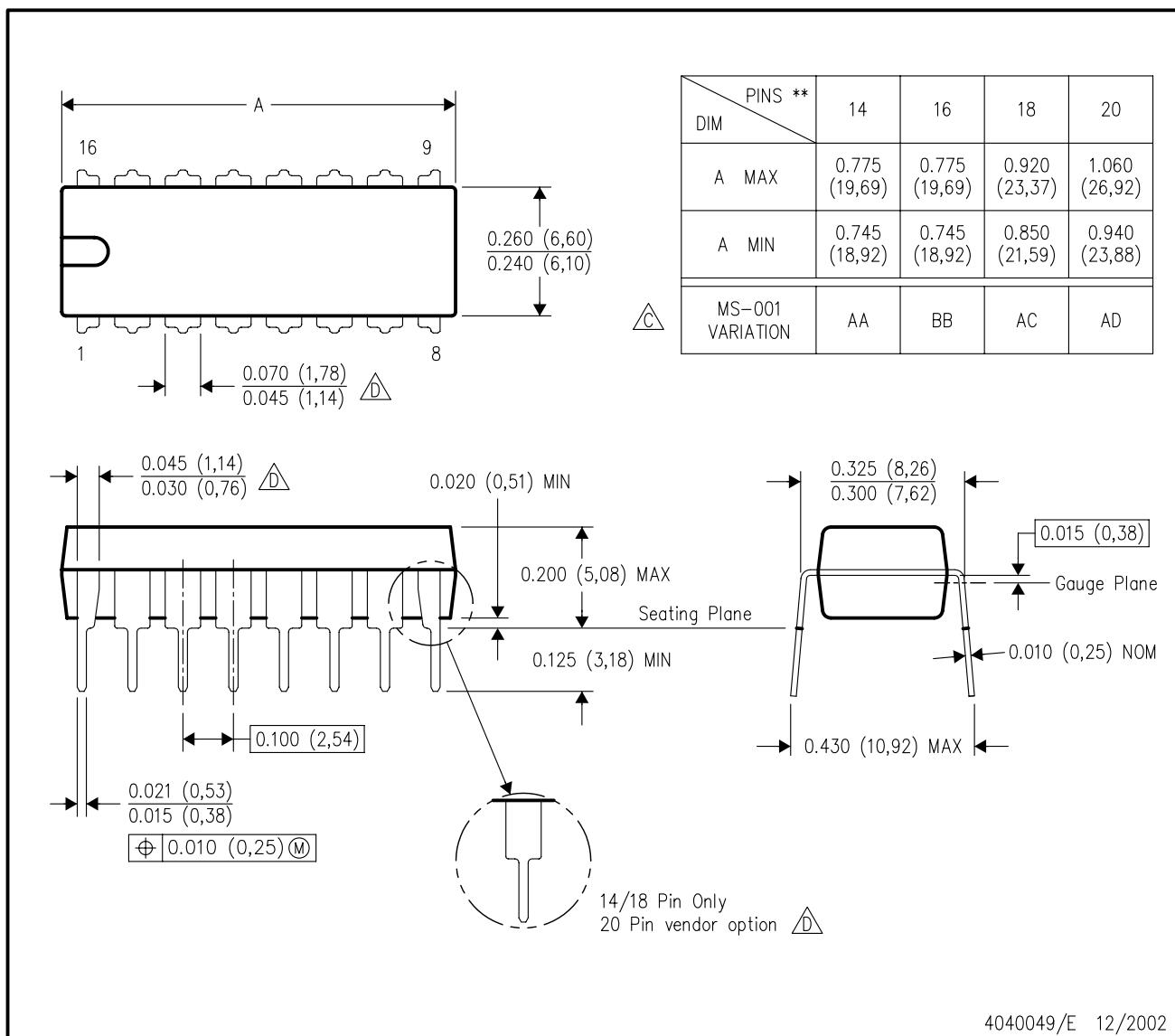
NOTES:

- All linear dimensions are in inches (millimeters).
- This drawing is subject to change without notice.
- This package can be hermetically sealed with a ceramic lid using glass frit.
- Index point is provided on cap for terminal identification only.
- Falls within MIL-STD 1835 GDFP1-F14 and JEDEC MO-092AB

## N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.

△ Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).

△ The 20 pin end lead shoulder width is a vendor option, either half or full width.

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